

METHOD AND STRUCTURE FOR CONNECTING GROUND/POWER NETWORKS TO PREVENT CHARGE DAMAGE IN SILICON ON INSULATOR

Abstract

A structure (and method) for an electronic chip, includes a first circuit design module having a first grid and a second circuit design module having a second grid. The first grid and the second grid are interconnected in a fabrication layer no later than a first metallization layer that accumulates a charge during a plasma process in the fabrication.